



United States Patent [19]

Orita et al.

[11] Patent Number:

6,117,700

BEST AVAILABLE CUP

[45] Date of Patent:

Sep. 12, 2000

[54] METHOD FOR FABRICATING SEMICONDUCTOR DEVICE HAVING GROUP III NITRIDE

[75] Inventors: Kenji Orita; Masahiro Ishida; Shinji

Nakamura; Masaaki Yuri, all of

Osaka, Japan

[73] Assignee: Matsushita Electronics Corporation,

Osaka, Japan

[21] Appl. No.: 09/389,024

[22] Filed: Sep. 2, 1999

[30] Foreign Application Priority Data

5533 T 4 69 7		774	\ 4 T	41 (00

[51] Int. Cl. H01L 21/00

[52] **U.S. Cl.** **438/46**; 438/22; 438/513; 438/688; 438/796

[56]

References Cited

U.S. PATENT DOCUMENTS

5,874,320 2/1999 Shih et al. .

FOREIGN PATENT DOCUMENTS

58-100471	6/1983	Japan .
6-9258	2/1994	Japan .
6-275868	9/1994	Japan .
6-350137	12/1994	Japan .
8-213656	8/1996	Japan .
10-144960	5/1998	Japan .
10-163529	6/1998	Japan .

Primary Examiner—Long Pham
Attorney, Agent, or Firm—Eric J. Robinson; Nixon Peabody
LLP

[57] ABSTRACT

First, n-type contact layer of GaN, n-type cladding layer of AlGaN, active layer of InGaN, first Mg-doped layer of AlGaN and second Mg-doped layer of GaN are grown in this order over a sapphire substrate. Thereafter, the substrate, including the second Mg-doped layer, is exposed to nitrogen plasma for about 40 minutes. As a result, Mg, which has been introduced into the first and second Mg-doped layers, is activated as an acceptor. Thus, p-type cladding layer and p-type contact layer with low resistance and excellent crystallinity can be formed out of the first and second Mg-doped layers, respectively.

15 Claims, 9 Drawing Sheets

